

SMD High Voltage Class II

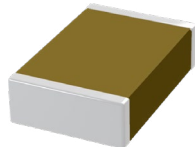
1KV - 15KV



SRT
MICROCÉRAMIQUE
MLCC CAPACITORS

APPLICATIONS

- Typical uses : passing, coupling, filtering, blocking



RoHS
compliant

FEATURES

- Temperature stable class II ceramic
- Custom voltage, package size, capacitance value on request
- Tested in accordance to CECC 32100 and AEC-Q200
- CECC 30700 et NFC 83-132 compliant
- Available in stack or radial
- Surface coating can be necessary to prevent surface arcing

ELECTRICAL PARAMETERS

ELECTRICAL CHARACTERISTICS :
at + 25°C unless otherwise specified

OPERATING TEMPERATURE :
- 55°C, + 125°C

TEMPERATURE COEFFICIENT :
± 15% with 0Vdc applied

DISSIPATION FACTOR :
≤ 2.5% at 1kHz for C ≥ 100pF

INSULATION RESISTANCE (IR) :
25°C/Un 10⁵ MOhm or 1000 Ohm-Farad whichever is less
125°C/Un 10⁴ MOhm or 100 Ohm-Farad whichever is less

DIELECTRIC STRENGTH TEST :
1.2Un for 5s with 50mA max charging current

QUICK REFERENCE DATA

	0805	1206	1210	1808	1812	1825	2220	2225	2825	3640	4040	5440	5550	6660	8060	80150	15080
Min	6.8 pF	10 pF	10 pF	10 pF	10 pF	33 pF	33 pF	33 pF	33 pF	100 pF	100 pF	100 pF	100 pF	100 pF	100 pF	180 pF	180 pF
1KV	5.6 nF	15 nF	47 nF	39 nF	120 nF	330 nF	330 nF	470 nF	560 nF	1.2 µF	1.2 µF	1.8 µF	2.2 µF	3.3 µF	3.9 µF	10 µF	10 µF
1.5KV	1.8 nF	5.6 nF	18 nF	15 nF	56 nF	120 nF	150 nF	180 nF	220 nF	470 nF	560 nF	680 nF	1.0 µF	1.2 µF	1.5 µF	3.9 µF	3.9 µF
2KV	820 pF	2.7 nF	8.2 nF	8.2 nF	22 nF	56 nF	68 nF	82 nF	120 nF	270 nF	270 nF	390 nF	470 nF	680 nF	820 nF	2.2 µF	2.2 µF
3KV		1.0 nF	2.7 nF	3.3 nF	8.2 nF	22 nF	27 nF	39 nF	47 nF	100 nF	120 nF	150 nF	180 nF	270 nF	330 nF	820 nF	820 nF
4KV		470 pF	1.5 nF	1.5 nF	4.7 nF	12 nF	15 nF	18 nF	27 nF	56 nF	56 nF	82 nF	100 nF	150 nF	180 nF	470 nF	470 nF
5KV				820 pF	2.7 nF	6.8 nF	8.2 nF	12 nF	15 nF	33 nF	33 nF	47 nF	56 nF	82 nF	100 nF	270 nF	270 nF
8KV				270 pF	1.0 nF	2.7 nF	2.7 nF	3.3 nF	4.7 nF	10 nF	12 nF	15 nF	18 nF	27 nF	33 nF	82 nF	82 nF
10KV							1.5 nF	1.8 nF	2.7 nF	5.6 nF	6.8 nF	8.2 nF	10 nF	15 nF	18 nF	47 nF	47 nF
12KV										3.9 nF	4.7 nF	5.6 nF	6.8 nF	10 nF	12 nF	33 nF	33 nF
15KV											2.7 nF	3.3 nF	3.9 nF	5.6 nF	6.8 nF	18 nF	18 nF

ORDERING INFORMATION

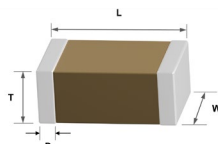
5440	Y	103	K	H	X	B	-
SIZE	DIELECTRIC	CAPACITANCE	TOLERANCE	VOLTAGE	TERMINATION	PACKAGING	SPECIAL PARAMETERS
0805 1206 1210 1808 1812 1825 2220 2225 2825 3033 3640 4040 4055 40100 5550 6660 8060 80150	Y = X7R	Expressed in picofarads (pF). The first two digits are significant, the third digit gives the number of noughts. Example : 102 = 1 000pF For special values R is used as decimal separator Example 12R7 = 12.7pF 1340R0 = 1340pF	J = ± 5% K = ± 10% M = ± 20%	G = 1KV O = 1.5KV H = 2KV T = 2.5KV I = 3KV K = 4KV L = 5KV 6 = 6KV 8 = 8KV 10 = 10KV 12 = 12KV 15 = 15KV	X = Nickel Tin F = Palladium-Silver P = Polymer Tin C = Copper Tin W = Nickel Gold	B = Reel V = Bulk	- BM = BME Dxx = Reliability spec Exx = Sorting spec

For other sizes, voltage, tolerance contact us.

DIMENSIONS IN MILLIMETERS

	0805	1206	1210	1808	1812	1825	2220	2225	2825	3640	4040	5440	5550	6660	8060	80150	15080
Length (L)	2.00 ± 0.2	3.20 ± 0.2	3.20 ± 0.2	4.60 ± 0.3	4.60 ± 0.3	4.60 ± 0.4	5.60 ± 0.4	5.60 ± 0.4	7.10 ± 0.4	9.15 ± 0.8	10.20 ± 0.8	13.70 ± 1.0	14.00 ± 1.0	16.80 ± 1.0	20.30 ± 1.0	20.30 ± 1.0	38.10 ± 1.0
Width (W)	1.25 ± 0.2	1.60 ± 0.2	2.50 ± 0.2	2.00 ± 0.2	3.20 ± 0.2	6.35 ± 0.3	5.10 ± 0.4	6.35 ± 0.4	6.35 ± 0.4	10.20 ± 0.8	10.20 ± 0.8	10.20 ± 1.0	12.70 ± 1.0	15.20 ± 1.0	15.20 ± 1.0	38.10 ± 1.0	20.30 ± 1.0
Thickness max(T)	1.40	1.70	2.50	2.20	3.30	3.60	4.30	4.30	4.30	4.30	4.30	4.30	4.30	4.30	4.30	4.30	4.30
Termination (P)	Min Max	0.25 0.70	0.25 0.70	0.25 0.80	0.25 0.80	0.25 0.80	0.25 0.80	0.25 1.00	0.25 1.00	0.25 1.50	0.25 1.50	0.25 1.50	0.25 1.50	0.25 1.50	0.25 1.50	0.25 1.50	0.25 1.50

For P termination (Polymer type) add 0.10mm to Length (L) and 0.05 to Width (W)



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SMD High Voltage Class II

1KV - 15KV



SRT
MICROCÉRAMIQUE
MLCC CAPACITORS

STANDARD SIZE : 0805 to 3640

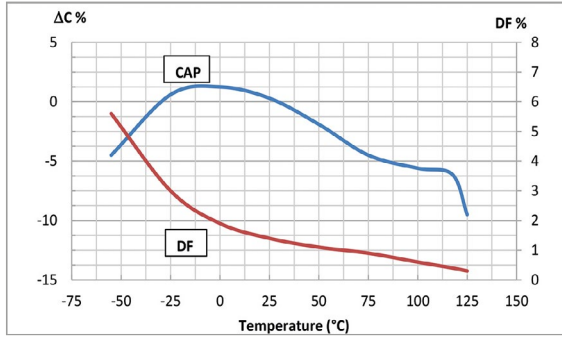
SIZE		0805		1206		1210		1808		1812		1825		2220		2225		3640					SIZE				
CODE	CAP	1KV	2KV	1.5KV	3KV	1.5KV	2KV	1.5KV	3KV	2KV	1.5KV	3KV	2KV	1.5KV	3KV	2KV	1.5KV	1KV	1.5KV	2KV	3KV	4KV	5KV	CAP	CODE		
																										220	22 pF
270	27 pF																									27 pF	270
330	33 pF																									33 pF	330
390	39 pF																									39 pF	390
470	47 pF																									47 pF	470
560	56 pF																									56 pF	560
680	68 pF																									68 pF	680
820	82 pF																									82 pF	820
101	100 pF																									100 pF	101
121	120 pF																									120 pF	121
151	150 pF																									150 pF	151
181	180 pF																									180 pF	181
221	220 pF																									220 pF	221
271	270 pF																									270 pF	271
331	330 pF																									330 pF	331
391	390 pF																									390 pF	391
471	470 pF																									470 pF	471
561	560 pF																									560 pF	561
681	680 pF																									680 pF	681
821	820 pF																									820 pF	821
102	1.0 nF																									1.0 nF	102
122	1.2 nF																									1.2 nF	122
152	1.5 nF																									1.5 nF	152
182	1.8 nF																									1.8 nF	182
222	2.2 nF																									2.2 nF	222
272	2.7 nF																									2.7 nF	272
332	3.3 nF																									3.3 nF	332
392	3.9 nF																									3.9 nF	392
472	4.7 nF																									4.7 nF	472
562	5.6 nF																									5.6 nF	562
682	6.8 nF																									6.8 nF	682
822	8.2 nF																									8.2 nF	822
103	10 nF																									10 nF	103
123	12 nF																									12 nF	123
153	15 nF																									15 nF	153
183	18 nF																									18 nF	183
223	22 nF																									22 nF	223
273	27 nF																									27 nF	273
333	33 nF																									33 nF	333
393	39 nF																									39 nF	393
473	47 nF																									47 nF	473
563	56 nF																									56 nF	563
683	68 nF																									68 nF	683
823	82 nF																									82 nF	823
104	100 nF																									100 nF	104
124	120 nF																									120 nF	124
154	150 nF																									150 nF	154
184	180 nF																									180 nF	184
224	220 nF																									220 nF	224
274	270 nF																									270 nF	274
334	330 nF																									330 nF	334
394	390 nF																									390 nF	394
474	470 nF																									470 nF	474
564	560 nF																									560 nF	564
684	680 nF																									680 nF	684
824	820 nF																									820 nF	824
105	1.0 μF																									1.0 μF	105
125	1.2 μF																									1.2 μF	125
155	1.5 μF																									1.5 μF	155
185	1.8 μF																									1.8 μF	185
225	2.2 μF																									2.2 μF	225
275	2.7 μF																									2.7 μF	275
335	3.3 μF																									3.3 μF	335
395	3.9 μF																									3.9 μF	395
475	4.7 μF																									4.7 μF	475
565	5.6 μF																									5.6 μF	565
685	6.8 μF																									6.8 μF	685
825	8.2 μF																									8.2 μF	825
106	10 μF																									10 μF	106
126	12 μF																									12 μF	126
156	15 μF																									15 μF	156

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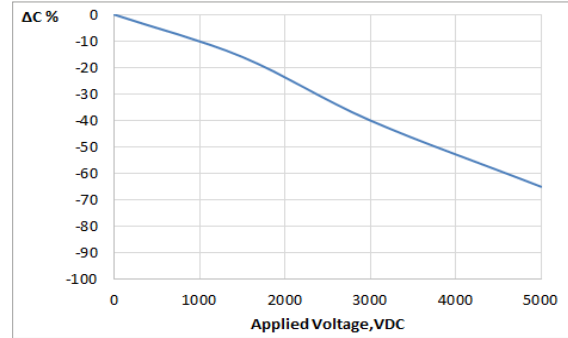


TYPICAL CHARACTERISTICS

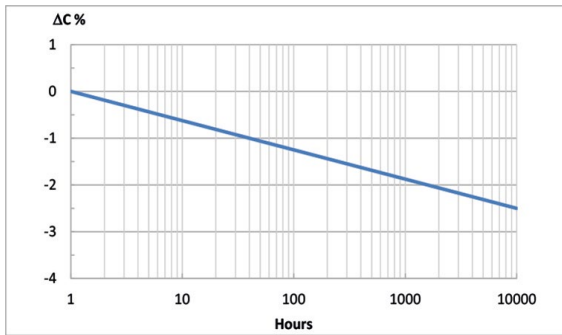
X7R Capacitance and factor vs temperature



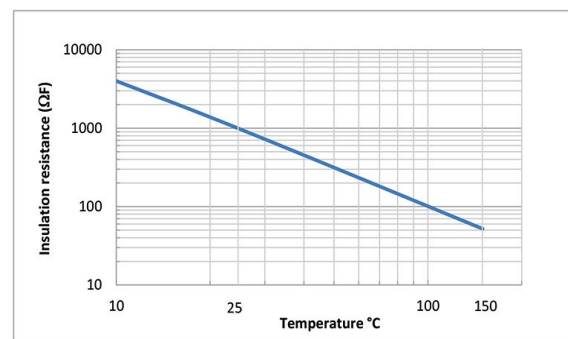
X7R Voltage coefficient of capacitance



X7R Aging



X7R Insulation resistance vs temperature



Different types of dielectrics display very different behaviours when it comes to withstanding power and heat, and don't demonstrate the same capacitance potential. SRT-Microcéramique proposes a wide range of ceramics. You'll find in the page below more information about what type of ceramic is better suited to your needs.

Class I Dielectrics

Class I Dielectrics are the most stable type and are used when the application demands highly stable performance and cannot allow electrical noise or dielectric loss. Variations of voltage and temperature have minimum consequences on this class of dielectrics, consequently, they are most used for DC blocking, decoupling applications as well as filtering with low capacitance.

Q (Code Q)

- Most stable type
- Low capacitance
- Good for avoiding electrical noise

NPO (Code A)

- Most stable type
- Lower capacitance
- Good for avoiding electrical noise

Class 1.5 Dielectrics

Close to Class II capacitance and as stable than Class I

N2T (Code P)

- Ultra stable
- No piezo electric effect
- High current pulse discharge

Class II Dielectrics

Class II Dielectrics display stable performance and possess a better volumetric efficiency than class I. Thus, they are used in bypassing, filtering, coupling and decoupling applications.

X7R (Code Y)

- Good volumetric efficiency
- High capacitance
- stable

BX/BY (Code X/2C1)

- Improved ESR
- Better voltage coefficient
- MIL specifications

X5R/X7S/X6S/Y5V (Code R/T/S/V)

- Highest capacitance per volume
- Less stable
- Low voltage

Dielectric	Class I		Class 1.5	Class II						
	High Q	NPO/COG	N2T	X7R	BX	2C1	X5R	X7S	X6S	Y5V
SRT Code	Q	A	P	Y	X	2C1	R	T	S	V
Type	Ultra Stable			Stable						
Temperature Range	-55°C +125°C (250°C)		-55°C +125°C			-55°C +85°C		-55°C +125°C	-55°C +105°C	-25°C +85°C
T° Coefficient no DC applied	± 30ppm		2200ppm ± 350	± 15%		± 20%	± 15%	± 22%		+30% -80%
T° Coefficient rated DC applied	-		-	-	+15 -25%	+20 -30%	-	-	-	-
Dielectric constant	10-100		450	2000-3000			3000-20000			
Dissipation Factor	0.01% 0.05%	0.05% 0.1%		1% 3.5%			2.5% 15%		5% 20%	
IR 25°C/Un	100 GΩ or 1000 Ω-F whichever is less						10 GΩ or 100 Ω-F whichever is less			
Dielectric strenght ≤200V	2.5 Ur 5 seconds 50mA max									
Dielectric strenght <500V	Ur + 250V 5 seconds 50mA max									
Dielectric strenght <1000V	1.5 Ur 5 seconds 50mA max									
Dielectric strenght ≥1000V	1.2 Ur 5 seconds 50mA max									
Piezo effect	No piezo			piezo effect						
Ageing	None			2% per decade	1% per decade		4% per decade	5% per decade		7% per decade
Tolerance	± 0.25pF ± 0.5pF ± 1% ± 2% ± 5% ± 10%			± 5% ± 10% ± 20%			± 10% ± 20%		-20% +80%	
Termination	X,C,H		X,F,P,C,W,H,I		X,P			X		

All our capacitors are available with a wide range of termination to fit your specific needs :

Tin (Code X)

- Standard termination
- ROHS
- Dipped Silver, Nickel barrier, Sn plated

Polymer (Code P)

- Flexible termination
- Improve bending tolerance
- ROHS
- Available on all components
- Designed for gluing

Silver-Palladium (Code F)

- Excellent contact properties
- Resist to leaching during hand soldering
- Dipped Silver-Palladium
- ROHS

Gold Flash (Code W)

- Glueing
- ROHS
- Max 0.2µm Gold Flash

Gold Thick (Code W)

- Microelectronic applications
- Wire Bonding/glueing
- ROHS
- Min 2.5µm Gold

Non Magnetic (Code C/CP)

- High Tesla Applications
- IRM, particule accelerators
- Dipped Silver, Copper barrier, Sn plated
- ROHS

Solderable Silver (Code Q)

- Medical or space application
- Whiskers free
- High temperature
- ROHS

Dipped SAC 305 (Code S/SP)

- Sn96.5 Ag3 Cu0.5
- Medical, space and oil application
- Whiskers free
- High reliability
- ROHS

Dipped Tin-Lead (Code H/HP)

- Sn62 Pb36 Ag2
- Medical or Oil application
- Whiskers free
- High reliability

Electrolytical Tin-Lead (Code I/IP)

- Minimum Pb 10%
- Medical or space application
- Whiskers free
- High reliability

TERMINATION	CODE	ROHS	NON MAGNETIC	IMPROVED BOARD FLEX	SOLDERING	GLUING	WIRE BONDING
Sn	X	0			0		
Polymer	P	0		0	0		
AgPd	F	0			0	0	
Gold Flash	W	0			0	0	
Gold Thick	G	0			0	0	0
Non Magnetic	C	0	0		0		
Solderable Silver	Q	0			0		
Dipped SnPb	H				0		
Dipped SAC	S	0			0		
Electrolytical SnPb	I				0		
Lead	-	0		0	0		
Non Magn Lead	C	0	0	0	0		
Lead Frame	-	0		0	0		
Non Magn Lead Frame	C	0	0	0	0		

0 = COMPLIANT

STORAGE

To prevent the damage of solderability of terminations, the following storage conditions are recommended :

Indoors under 5 ~ 40°C and 20% ~ 70% RH.

No harmful gases containing sulfuric acid, ammonia, hydrogen sulfide or chlorine.

Packaging should not be opened until the capacitors are required for use. If opened, the pack should be re-sealed as soon as possible. Taped products should be stored out of direct sunlight, which might promote deterioration in tape or adhesion performance. The product is recommended to be used within 24 months after shipment. Extended shelf life over this period require a solderability check before use.

HANDLING

Chip capacitors are dense, hard, brittle, and abrasive materials. They are liable to suffer mechanical damage, in the form of cracks or chips. Chip Capacitors should be handled with care to avoid contamination or damage. To use vacuum or plastic tweezers to pick up or plastic tweezers is recommended for manual placement. Tape and reeled packages are suitable for automatic pick and placement machine.

PREHEAT

In order to minimize the risk of thermal shock during soldering, a carefully controlled preheat is required.

The rate of preheat should not exceed 3°C per second.

SOLDERING FLUX

Use mildly activated rosin RA and RMA fluxes, but do not use activated flux. The amount of solder in each solder joint should be controlled to prevent the damage of chip capacitors caused by the stress between solder, chips, and substrate.

SOLDERING TYPE

Lead containing solders, such as Sn60, Sn62 or Sn63 and lead free solders, such as SnAgCu, can all be used with our MLCCs.

In case of non-magnetic termination code C, use lead containing or lead (Pb)-free SAC305 solders.

SOLDERING HEIGHT

The solder climbing minimum height is suggesting to 25% of chip thickness or 500um whichever is less.

(Reference from IPC-610E)

COOLING

After soldering, cool the chips and the substrate gradually to room temperature. Natural cooling in air is recommended to minimize stress in the solder joint.

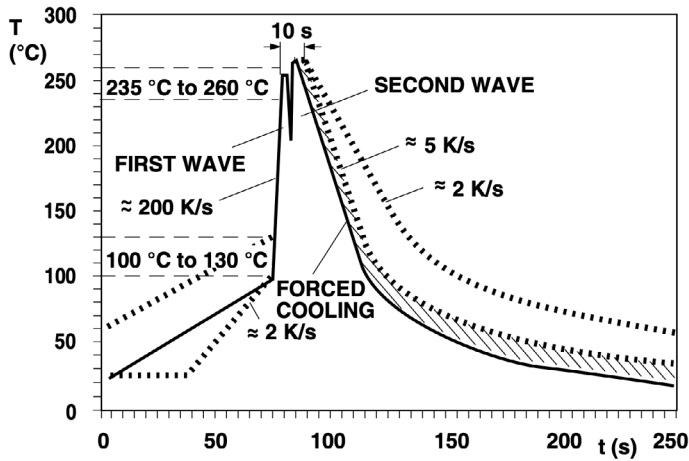
CLEANING

All flux residues must be removed by using suitable electronic-grade vapor-cleaning solvents to eliminate contamination that could cause electrolytic surface corrosion. Good results can be obtained by using ultrasonic cleaning of the solvent. The choice of the proper system is depends upon many factors such as component mix, flux, and solder paste and assembly method. The ability of the cleaning system to remove flux residues and contamination from under the chips is very important.

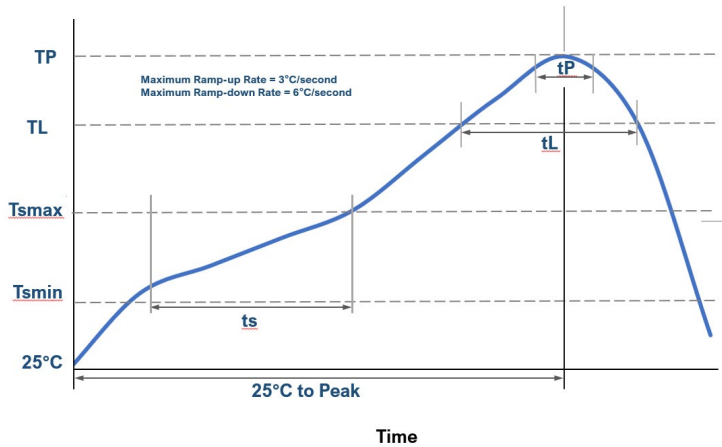
SOLDERING CONDITIONS

SIZE	THICKNESS	WAVE	REFLOW
0402	All	0	0
0505	All	0	0
0603	All	0	0
0805	< 1.25mm	0	0
0805	≥ 1.25mm	0	0
1111	< 1.25mm	0	0
1111	≥ 1.25mm	0	0
1206	< 1.25mm	0	0
1206	≥ 1.25mm	0	0
1210	< 1.25mm	0	0
1210	≥ 1.25mm	0	0
larger than 1210	All	0	0
High compact	All	0	0

WAVE SOLDERING PROFILE

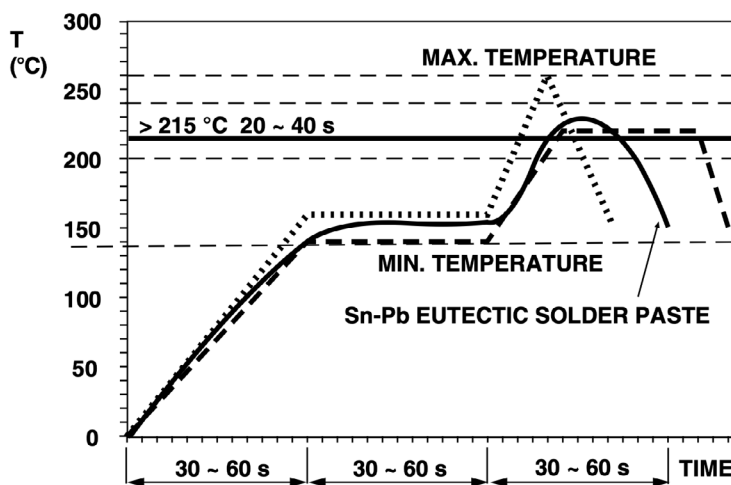


LEADFREE REFLOW SOLDERING PROFILE



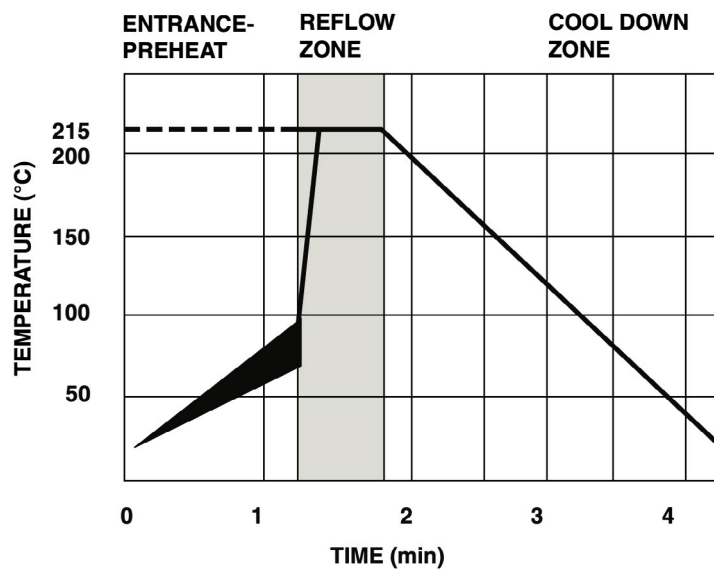
PROFILE FEATURE	LEAD FREE (SAC 305)
Tsmin	150°C
Tsmax	190°C
Time from Tsmin to Tsmax	60 - 120 seconds
Ramp-up Rate	3°C/second max
Liquidous Temperature	217°C
Time above Liquidous	60 - 120 seconds
Peak Temperature	250°C
Time within 5°C of maximum	10 seconds max
Peak Temperature	250°C
Ramp-down Rate	6°C/second max
Time 25°C to Peak	8min max

SNPB REFLOW SOLDERING PROFILE



VAPOUR PHASE REFLOW PROFILE

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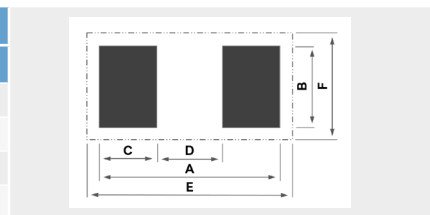
HAND SOLDERING

Hand soldering is not recommended as the thermal shock may cause a crack, however if used the following recommendations should be taken :

- Soldering iron tip diameter ≤ 3.0 mm and wattage max. 20W.
- The Capacitors shall be pre-heated to 150°C and that the temperature gradient between the devices and the tip of the soldering iron.
- Tip temperature ≤ 280 °C and should't be applied for more than 5 seconds.
- The required amount of solder shall be melted on the soldering tip.
- The tip of iron should not contact the ceramic body directly.
- The Capacitors shall be cooled gradually at room temperature after soldering.
- Forced air cooling is not allowed.

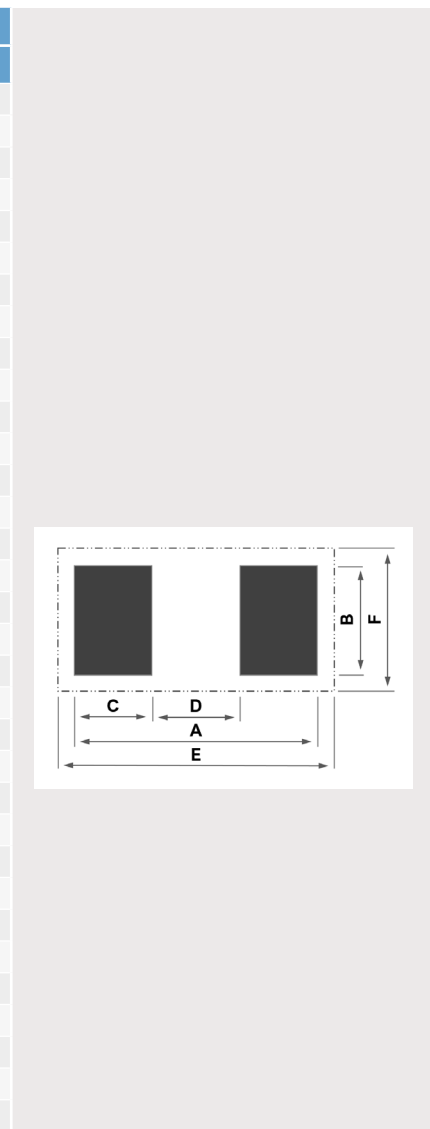
TYPICAL SMD FOOTPRINT WAVE SOLDERING

SIZE	FOOTPRINT DIMENSIONS IN MM					
	A	B	C	D	E	F
0603	2.40	0.80	0.70	1.00	3.10	1.40
0805	3.20	1.30	0.90	1.40	4.10	1.85
1206	4.80	1.70	1.25	2.30	5.90	2.25
1210	4.80	2.60	1.25	2.30	5.90	3.15



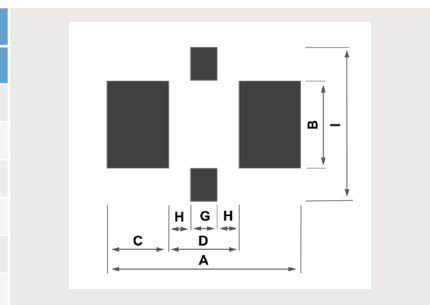
TYPICAL SMD FOOTPRINT REFLOW SOLDERING

SIZE	FOOTPRINT DIMENSIONS IN mm					
	A	B	C	D	E	F
0201	0.65	0.30	0.21	0.23	0.90	0.60
0204	1.00	1.00	0.30	0.40	1.25	1.45
0402	1.50	0.50	0.40	0.70	1.75	0.95
0306	1.30	1.60	0.40	0.50	1.55	2.05
0404	1.50	1.00	0.40	0.70	1.75	1.45
0504	1.90	1.00	0.40	1.10	2.15	1.45
0505	1.90	1.30	0.50	0.80	2.15	1.75
0508	1.90	2.00	0.50	0.90	2.15	2.55
0603	2.30	0.80	0.60	1.10	2.55	1.35
0612	2.30	3.20	0.60	1.10	2.55	3.75
0805	2.90	1.25	0.90	1.10	3.15	1.80
1206	4.10	1.60	0.90	2.30	4.35	2.25
1210	4.10	2.50	1.00	2.10	4.35	3.15
1808	5.50	2.10	1.20	3.10	5.75	2.75
1812	5.50	3.30	1.20	3.10	5.75	3.95
1825	5.50	6.55	1.20	3.10	5.75	7.20
2211	6.80	3.00	1.40	4.00	7.05	3.65
2220	6.80	5.40	1.40	4.00	7.05	6.05
2225	6.80	6.70	1.65	3.50	7.05	7.50
2525	7.70	6.75	1.65	4.40	7.95	7.55
2825	8.40	6.70	1.65	5.10	8.65	7.50
3033	9.00	8.80	1.95	5.10	9.25	9.60
3640	10.55	10.70	2.35	5.85	10.80	11.50
4040	11.60	10.70	2.35	6.90	11.85	11.50
40100	11.60	26.20	2.35	6.90	11.85	27.00
5550	15.50	13.20	2.35	10.80	15.75	14.00
6080	16.70	20.80	2.35	12.00	16.95	21.60
6660	18.30	15.70	2.35	13.60	18.55	16.50
8060	21.90	15.70	2.35	17.20	22.15	16.50
80150	21.90	38.90	2.35	17.20	22.15	39.70
HIGH COMPACT 1210	4.15	2.60	1.15	1.85	5.05	3.30
HIGH COMPACT 1812	5.75	3.40	1.35	3.05	6.70	4.20
HIGH COMPACT 2220	6.80	5.50	1.70	3.40	7.70	6.30



TYPICAL FILTER FOOTPRINT REFLOW SOLDERING

SIZE	FOOTPRINT DIMENSIONS IN mm						
	A	B	C	D	G	H	I
0603	2.30	0.80	0.45	1.40	0.60	0.40	1.50
0805	2.90	1.25	0.90	1.80	0.80	0.50	2.00
1206	4.10	1.60	0.90	2.40	1.00	0.70	3.00
1806	5.50	1.60	1.20	3.20	1.00	1.10	3.00
1812	5.50	3.30	1.20	3.90	1.50	1.20	4.80
2220	6.80	5.40	1.40	4.50	1.50	1.50	7.00





ORDERING INFORMATION

SRMC	0603	Y	102	J	A	-	L	040	-	-	-	B	-
SERIE	SIZE	DIELECTRIC	CAPACITANCE	TOLERANCE	VOLTAGE	TERMINAISON	FORM	HEIGHT	LEADS	COATING	CUR-RENT	PACKAGING	SPECIAL
-	0201	Q = High Q	Expressed in picofarads (pF)	A = ± 0.05pF/0.1%	Y = 4V	- = Sn lead/lead frame	-	020	-	-	-	B = Reel	-
FK	0204	A = NPO		B = ± 0.1pF	R = 6.3V	X = Nickel Tin	J	030	2 to 10	I = Conformal-Coating	1	V = Bulk	BM = BME
FH	0402	P = N2T	The first two digits are significant,	C = ± 0,25pF	Q = 10V	F = Palladium-Silver	L	040	B	H = EpoxyCoating	2	T = Tray Package	Dxx = Reliability spec
SREV	0303	X = BX	the third digit gives the number of noughts	D = ± 0,5pF	J = 16V	P = Polymer Tin (Flex)	D	050				W = Waffle Pack	Exx = Sorting spec
MCF	0306	Y=X7R		E = ± 0.5%	X = 25V	C = Copper Tin (Non magnetic)	M	060					H = High Reliability
M2F	0404	BY=2C1		F = ± 1%	Z = 35V	CP = Copper Polymer Tin (Non magnetic)	T = 2	070					Q = Anti-Arcing
MPF	0505	T = X7S	Example : 102 = 1 000pF	G = ± 2%	A = 50V	W = Nickel Gold Flash	leads	080					E = Anti Bending
SRMC	0508	S = X5R		J = ± 5%	U = 63V	G = Nickel Gold Thick	U = 4	090					Z = Anti-Arcing + Anti-Bending
SRTV	0603	R = X6S		K = ± 10%	B = 100V	HP = Dipped SnPb Polymer	leads	100					
SR	0612	V = Y5V	For special values R is used as decimal separator	M = ± 20%	C = 200V	H = Dipped SnPb		110					
SA	0805	U = X8R	Example 12R7 = 12.7pF	Z = -20% +80%	P = 250V	S = Dipped SAC		120					
H	1206		Example 1340R0 = 1340pF		D = 300V	SP = Polymer Dipped SAC		130					
	1210				E = 500V	I = Electrolytic SnPb		140					
	1808				F = 630V	IP = Polymer Electrolytical SnPb		160					
	1812				G = 1000V	Q = Solderable Silver		180					
	1825				O = 1500V	M = Microstrip							
	2211				H = 2000V	A = Axial Ribbon							
	2220				T = 2500V	R = Radial Ribbon							
	2225				I = 3000V	U = Axial Wire							
	2325				K = 4000V	V = Radial Wire							
	2525				L = 5000V	CM = Microstrip (Non magnetic)							
	2825				6 = 6000V	CA = Axial Ribbon (Non magnetic)							
	3033				S = 7200V	CR = Radia Ribbon (Non magnetic)							
	3640				8 = 8000V	CU = Axial Wire (Non magnetic)							
	4040				10 = 10000V	CV = Radial Wire (Non magnetic)							
	40100				12 = 12000V								
	5550				15 = 15000V								
	6080												
	6660												
	7274												
	8060												
	80150												
	15080												
	40 to 94												

RELIABILITY

OPTIONAL CODE	TESTING DETAIL
D03	Burn-In 100% 125° 168H, no default allowed
D05	Burn-In 100% 125° 168H, less than 5% default allowed VRT CEI 68-2-14 10 cycles 0V -55°C/+125°C, less than 5% default allowed 20 pieces life test 125°C, 1.5Un, 1 default allowed
D20	AECQ-200
D30	Screened and LAT according to ECSS-3009 for space application
D32	Evaluation version for space development according to ECSS-2310
COTS1	Class 1 COTS+ according to ECSS-Q-ST-60-13C-Rev1
COTS2	Class 2 COTS+ according to ECSS-Q-ST-60-13C-Rev1
COTS3	Class 3 COTS+ according to ECSS-Q-ST-60-13C-Rev1

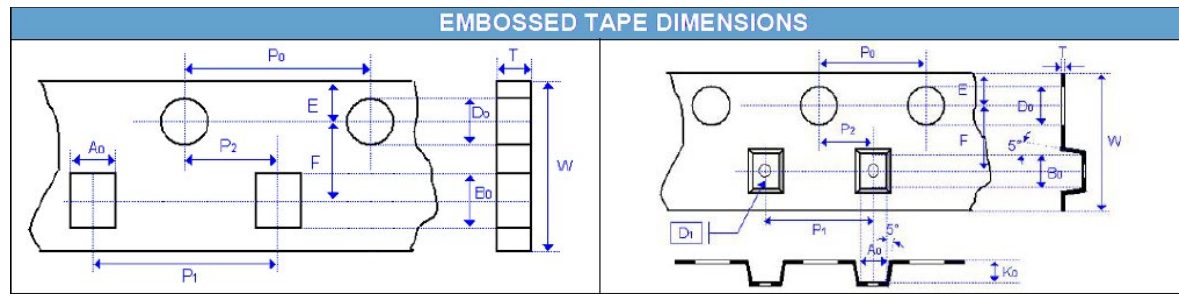
SORTING

OPTIONAL CODE	SORTING DETAIL
E01	2 cells sorting 0 to +2,5 & +2,5 to +5 (% or pF according to value)
E02	4 cells sorting -5 to -2,5 ; -2,5 to 0 ; 0 to +2,5 & +2,5 to 5 (% or pF according to value)
E21	2% cells

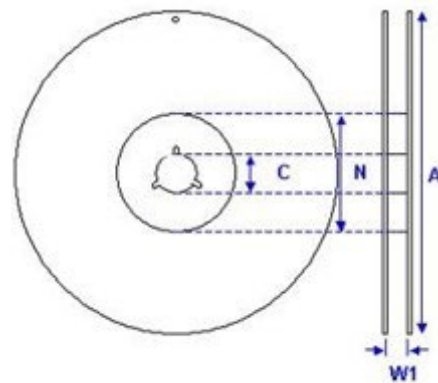


PACKAGE DIMENSION AND QUANTITY

SIZE	THICKNESS	PAPER TAPE		PLASTIC TAPE	
		7 REEL	13 REEL	7' REEL	13 REEL
0402	0.5 ± 0.05	10 K	50 K		
0504	0.6 ± 0.05			4K	15K
	0.9 ± 0.05			4K	15K
0603	0.7 ± 0.07	4K		4K	15K
	0.9 ± 0.07	4K	15K	4K	15K
	0.9 ± 0.07			4K	15K
	1.1 ± 0.07			4K	15K
0805	0.8 ± 0.07	4K	15K	4K	15K
	0.9 ± 0.07			4K	10K
	1.1 ± 0.07			3K	10K
	1.3 ± 0.07			3K	10K
1206	1.1 ± 0.1			3K	10K
	1.4 ± 0.1			3K	8K
	1.8 ± 0.1			2K	8K
1210	1.4 ± 0.1			3K	8K
	1.8 ± 0.1			1K	6K
1808	1.4 ± 0.1			3K	8K
1812	1.6 ± 0.1			2K	8K
	2.1 ± 0.1			1K	6K
	2.8 ± 0.1			1K	6K
2220	1.8 ± 0.1			1K	6K
	3.0 ± 0.1			0.5K	2K
2225	3.0 ± 0.1			0.5K	2K
3033	3.0 ± 0.1			0.5K	2K
3640	3.0 ± 0.1			0.5K	2K
5440	3.9 ± 0.1				0.5K - 1K
HIGH COMPACT 1210				1K	6K
HIGH COMPACT 1812				1K	6K
HIGH COMPACT 2220				0.5K	2K



REEL SIZE	7	7	13
C	13.0 +0.5/-0.2	13.0 +0.5/-0.2	13.0 +0.7/-0.3
W1	8.4 +1.5/-0	12.4 +2.0/-0	8.4 +2.0/-0
A	178.0 ±0.10	178.0 ±0.10	330.0 ±1.0
N	60.0 ±1.0	80.0 ±1.0	100 ±1.0



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RELIABILITY PRINCIPLES OVERVIEW GENERAL PRODUCTION

In order to guarantee highly reliable products to their customers, SRT-Microcéramique follows a strict quality policy which is explained below :

- According to AECQ philosophy, each component belongs to a family, which most restrictive members (four corners) have been fully qualified.
- PME components are produced in our Vendôme facility, with very stable process and equipments, in order to ensure Reliability and reproductibility.
- Reliability is based on batch tests, new product or equipment-specific qualifications and periodic requalifications.
- In addition to those regular tests, our quality departement launches regular accelerated tests to further deepens our reliability datas.
- Tests and qualifications of our standard products are based on AECQ methodology and are qualified according to the following limits.
- In accordance to AECQ methodology, specifics tests and limits can be adapted to fit our clients' needs.
- A whole range of stricter reliability tests can be offered for high Reliability products (burn-in, shocks, pulses...) for medical, space and defense applications.
- Based on our reliability database, FIT datas can be provided if necessary.

PRODUCTION CONTROL

Test conducted on each lot according to AECQ-200 framework

FREQUENCY	TEST/STRESS	REFERENCE	AEC-Q	DETAIL
100%	Capa, DF, IR	CECC-32100-4.6		according to datasheet
100%	Visual	CECC-32100-4.5	AEC-Q200-9	no visual defects
50/lot	DPA		AEC-Q200-5	internal component integrity
5/lot	Dimension	CECC-32100-4.5	AEC-Q200-5	according to datasheet
5/lot	Resistance to soldering heat	CECC-32100-4.10	AEC-Q200-15	
5/lot	Solderability	CECC-32100-4.11	AEC-Q200-18	
10/lot	Voltage proof	CECC-32100-4.6.4		
1/ceramic lot	Temperature coefficient	CECC 32100-Prgph4,7		according to datasheet

QUALIFICATIONS

Each component family has been qualified according to CECC and AECQ tests methodology, which are renewed on a periodic basis.

FREQUENCY	TEST/STRESS	REFERENCE	AEC-Q	DETAIL
Qualif	Electrical Characterization	CECC-32100-4.6 4.7	AEC-Q200-19	measure before test according to datasheet and after test according to post environmental limits
Qualif	Temperature Cycling	JESD22 Method-JA method 104	AEC-Q200-4	1,000 cycles -55°C to +125°C Measurement at 24 ± 2 hours after test conclusion
Qualif	Biased Humidity	MIL-STD-202 Method 103	AEC-Q200-7	1,000 hours 85°C/85%RH. Rated voltage. Measurement at 24 ± 2 hours after test conclusion
Qualif	Operational Life	MIL-STD-202 Method 108 condition D	AEC-Q200-8	1,000 hours at 125°C with applied Voltage : 2xRV RV≤500V, 1.2xRV 500V<RV≤1250V, RV RV>1250V
Qualif	High Temperature Exposure (Storage)	MIL-STD-202 Method 108	AEC-Q200-3	1,000 hours at 150°C with 0V. Measurement at 24 ± 2 hours after test conclusion
Qualif	Terminal Strength	CECC-32100-4.8	AEC-Q200-6	1.8kg 60 seconds
Qualif	Vibration	MIL-STD-202 Method 204	AEC-Q200-14	5g 20min 12cycles 3 orientations 10-2000Hz
Qualif	Board Flex	CEC 32100-4.9	AEC-Q200-21	3mm Type 1, 2mm Type 2, Measurement at 24 ± 2 hours after test conclusion

POST ENVIRONMENTAL STRESS LIMIT

DIELECTRIC	DISSIPATION FACTOR (MAXIMUM)	CAPACITANCE SHIFT	INSULATION RESISTANCE
NPO	≤ 4 10 ⁻³	±2%	10% initial limit
N2T	≤ 6 10 ⁻³	±4%	10% initial limit
X7R	≤ 0.035	±15%	10% initial limit

SPACE LEVEL COMPONENT SCREENED AND QUALIFIED ACCORDING TO ESCC-3009

SRT-Microcéramique can propose a wide range of BME and PME component qualified and tested according to ESCC-3009 standard for space projects. Both for development en evaluation (D32) and flight ready with full lot validation and ESCC standard documentation. Specific qualification programmes can be included to meet final customer requirement.

PRODUCTION CONTROL/SCREENING

Tests conducted on each lot and screening for evaluation components D32 and flying components D30

FREQUENCY	TEST/STRESS	REFERENCE	DETAIL
Lot	DPA	ESCC-23400	Construction analysis
3/Lot	Dimension/weight	ESCC-20400/20500	Dimension in spec/max weight in spec
100%	Burn-In	ESCC-3009	168H, max T°, 2Ur Ur<500V, 1.5Ur Ur=500V, 1.3Ur 500V<Ur≤1250V, 1Ur Ur>1250V (fail<5%)
100%	Room Temperature Electrical Measurements	ESCC-3009	Cp, DF, IR, VP according to datasheet
5/lot	High and Low Temperatures Electrical Measurements	ESCC-3009	0 fail
100%	Visual Inspection	ESCC-20400/20500	

LOT VALIDATION

Lot validation for flying components D30

FREQUENCY	TEST/STRESS	REFERENCE	DETAIL
20/Lot	PCB Mounting, Rapid Change of Temperature, Steady State Humidity, external visual inspection	ESCC-3009/ IEC 60384-1/IEC 60068-2-14	
20/Lot	PCB Mounting, Life test	ECSS-3009/IEC 60384-1	1000H, max T°, 2Ur Ur<500V, 1.5Ur Ur=500V, 1.3Ur 500V<Ur≤1250V, 1Ur Ur>1250V
6/Lot	PCB Mounting, Temperature Characterisation, Robustness of Terminations	ESCC-3009/ IEC 60068-2-14/IEC 60384-1	
6/Lot	Solderability, Permanence of Marking	ECSS-3009/ IEC 60068-2-58/ ECSS-24800	

SPACE LEVEL COMPONENT SCREENED ACCORDING TO COTS+ ECSS-Q-ST-60-13C-REV1

SRT-Microcéramique can apply the COTS+ qualification framework to any suitable component AEQ-200 or not, to make them fly ready, offering a wide range of possibilities at competitive cost, either in Class 1 (COTS1), Class 2 (COTS2) or Class 3 (COTS3).

EVALUATION/SCREENING/LAT

Class 1 (COTS1), Class 2 (COTS2), Class 3 (COTS3)

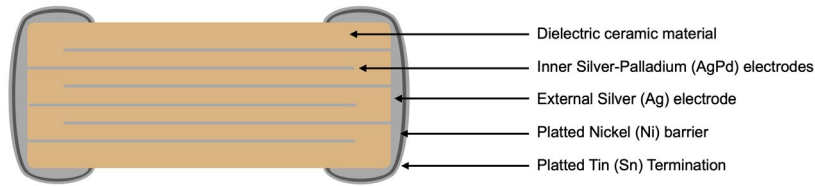
AECQ-200	CLASS 1	CLASS 2	CLASS 3	CATEGORY	TEST TYPE	SAMPLE	PROCEDURE
Yes	X	X	X	Evaluation	Construction Analysis	5	ESCC21001
Yes	X	X	X	Evaluation	Temperature characterization	5	ESCC3009 8.10
Yes	X			Evaluation	Life Test 2000h	40	ESCC3009 8.6 + 8.9
Yes	X			Screening	Complete screening	100%	ESCC3009 chart F3
Yes	X	X	X	LAT	DPA	3	ESCC21001
Yes	X	X		LAT	Life Test 1000h	20	ESCC3009 8.6 + 8.9
No	X	X	X	Evaluation	Construction Analysis	5	ESCC21001
No	X	X	X	Evaluation	Temperature characterization	5	ESCC 3009 8.10
No	X	X		Evaluation	Complete evaluation	72	ESCC 3009 chart F4
No			X	Evaluation	Life Test 1000h	40	ESCC3009 8.6 + 8.9
No	X	X	X	Screening	Complete screening	100%	ESCC3009 chart F3
No	X	X	X	LAT	DPA	3	ESCC21001
No	X			LAT	Complete LAT	52	ESCC 3009 chart F4
No		X	X	LAT	Life Test 1000h	20	ESCC3009 8.6 + 8.9

TINNING

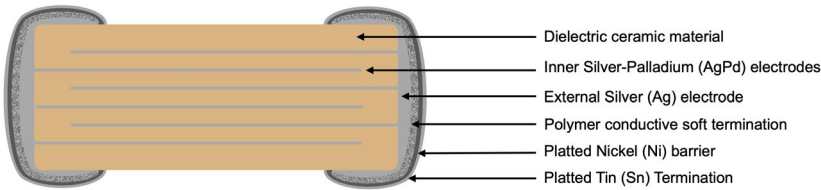
All component for space application can be proposed with dipped SnPb termination (Sn62 Pb36 Ag2) or SAC 305 (Sn96.5 Ag3 Cu0.5) for maximum reliability and whiskers avoidance.

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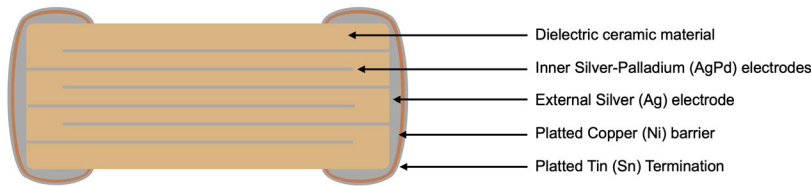
PME (Precious Metal Electrodes)



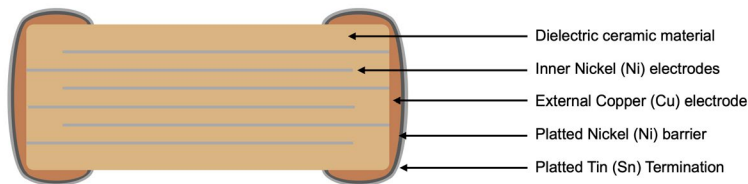
PME (Precious Metal Electrodes) Polymer Soft Termination



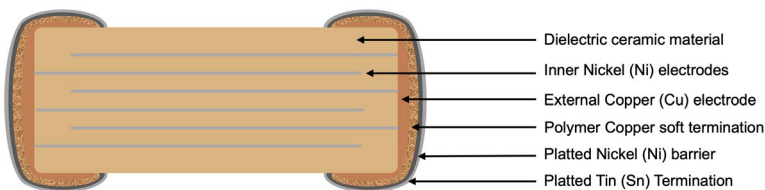
PME (Precious Metal Electrodes) Non Magnetic



BME (Basis Metal Electrodes) code BM



BME (Basis Metal Electrodes) code BM Polymer Soft Termination



REACH Compliance

- SRT-Microcéramique delivers non-chemical articles only.
- These contain no substances which are intended to be released under normal or reasonably foreseeable conditions of use according to Reach article 7(1).

SRT-Microcéramique confirms hereby that our products contain none of the substances which are listed in the present candidate list of the European Chemicals Agency (ECHA), above a concentration of 0.1% by weight of the whole component.

Candidate list of substances (European Chemicals Agency ECHA) :
<http://echa.europa.eu/fr/candidate-list-table>

ROHS COMPLIANCE

SRT-Microcéramique herewith confirms that RoHS-compliant SRT-microcéramique products are conforming to the following EU directives:
EU directive 2015/863/EU EU directive 2011/65/EU EU directive 2003/11/EC

Following restricted materials are not used and do not exceed the legal limits: Lead (Pb, see exemptions),

- Mercury (Hg)
- Cadmium (Cd)
- Chromium (Cr VI)
- Polybrominated biphenyls (PBB) Polybrominated diphenyl ethers (PBDE) Bis(2-Ethylhexyl) phthalate (DEHP) Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP) Diisobutyl phthalate (DIBP)

Exemptions: The following exemptions according to the RoHS annexe are applicable:

Identity 7(a) :

- Lead in high melting temperature type solders (i.e lead-based alloys containing 85% by weight or more lead).

Identity 7(c)-I :

- Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.

The components are suitable for a lead-free process according to EN 60068-2-58 and in accordance with the IPC/JEDEC standard J-Std-020D. The lead free process has been tested using solder alloy Sn96.5Ag3Cu0.5

Export controls and dual-use regulations

Some SRT-Microcéramique components fall under 'dual-use' items under international export controls definition - those that can be used for civil or military purposes which meet certain specified technical standards.

The defining criteria for a dual use component is one with a voltage rating of >750Vdc and a capacitance value of >250nF when measured at 750Vdc and a series inductance <10nH. Components defined as dual-use under the above criteria may require a licence for export across international borders. Please contact us for further information on specific part numbers.

ISO9001:2015

In their design, research and development as well as the manufacturing of MLCC capacitors, customer service and distribution SRT-Microcéramique uses and maintains a Management System audited and certified in accordance to : **ISO9001:2015**

You may contact us for any inquiry regarding the regulations and compliance listed above.